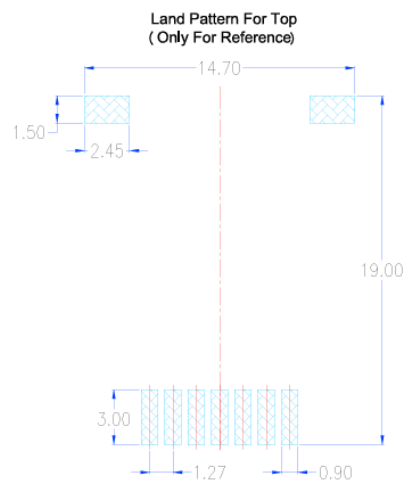
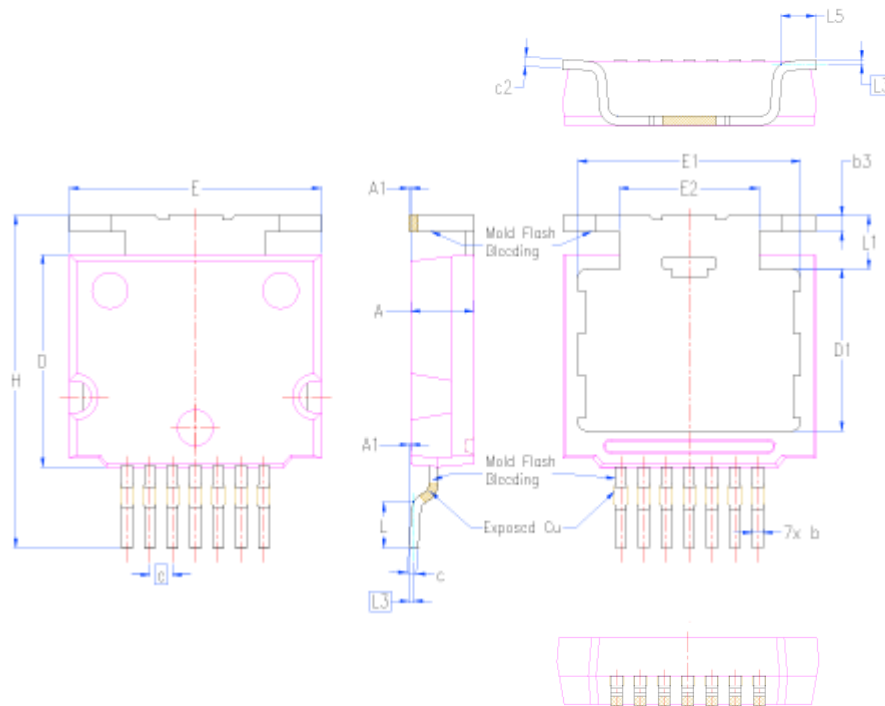


Package Dimensions



Product	SiC MOSFET	Package	HU3PAK
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- Note:
1. All Dimensions Are In mm.
 2. Dimension D & E Do Not Include Mold Flash.
Mold Flash Shall Not Exceed 0.127mm Per Side.
These Dimensions Are Measured At The Outermost Extreme Of The Plastic Body.
 3. Thermal Pad Contour Optional Within Dimensions L1, D1 & E1.
 4. Dimension D1 & E1 Establish A Minimum Mounting Surface For The Thermal Pad.
 5. is Exposed Cu.

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	3.40	3.50	3.60
A1	0.00	0.10	0.25
b	0.50	0.60	0.70
b3	0.80	0.90	1.00
c	0.40	0.50	0.60
c2	0.40	0.50	0.60
D	11.70	11.80	11.90
D1	8.80	9.00	9.10
E	13.90	14.00	14.10
E1	12.30	12.40	12.50
E2	7.75	7.80	7.85
e	1.27 BSC		
H	18.00	18.50	19.00
L	2.30	2.50	2.75
L1	--	3.05	--
L3	--	0.26	--
L5	1.70	1.90	2.15